



Welcome to **E-XFL.COM**

Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	1664
Number of Logic Elements/Cells	16640
Total RAM Bits	212992
Number of I/O	488
Number of Gates	1052000
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	672-BBGA
Supplier Device Package	672-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep20k400efc672-2x

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

- Flexible clock management circuitry with up to four phase-locked loops (PLLs)
 - Built-in low-skew clock tree
 - Up to eight global clock signals
 - ClockLock[®] feature reducing clock delay and skew
 - ClockBoost[®] feature providing clock multiplication and division
 - ClockShift™ programmable clock phase and delay shifting

Powerful I/O features

- Compliant with peripheral component interconnect Special Interest Group (PCI SIG) PCI Local Bus Specification, Revision 2.2 for 3.3-V operation at 33 or 66 MHz and 32 or 64 bits
- Support for high-speed external memories, including DDR SDRAM and ZBT SRAM (ZBT is a trademark of Integrated Device Technology, Inc.)
- Bidirectional I/O performance ($t_{CO} + t_{SU}$) up to 250 MHz
- LVDS performance up to 840 Mbits per channel
- Direct connection from I/O pins to local interconnect providing fast t_{CO} and t_{SU} times for complex logic
- MultiVolt I/O interface support to interface with 1.8-V, 2.5-V, 3.3-V, and 5.0-V devices (see Table 3)
- Programmable clamp to V_{CCIO}
- Individual tri-state output enable control for each pin
- Programmable output slew-rate control to reduce switching noise
- Support for advanced I/O standards, including low-voltage differential signaling (LVDS), LVPECL, PCI-X, AGP, CTT, stubseries terminated logic (SSTL-3 and SSTL-2), Gunning transceiver logic plus (GTL+), and high-speed terminated logic (HSTL Class I)
- Pull-up on I/O pins before and during configuration

Advanced interconnect structure

- Four-level hierarchical FastTrack[®] Interconnect structure providing fast, predictable interconnect delays
- Dedicated carry chain that implements arithmetic functions such as fast adders, counters, and comparators (automatically used by software tools and megafunctions)
- Dedicated cascade chain that implements high-speed, high-fan-in logic functions (automatically used by software tools and megafunctions)
- Interleaved local interconnect allows one LE to drive 29 other LEs through the fast local interconnect

Advanced packaging options

- Available in a variety of packages with 144 to 1,020 pins (see Tables 4 through 7)
- FineLine BGA® packages maximize board space efficiency

Advanced software support

 Software design support and automatic place-and-route provided by the Altera® Quartus® II development system for

General Description

APEXTM 20K devices are the first PLDs designed with the MultiCore architecture, which combines the strengths of LUT-based and product-term-based devices with an enhanced memory structure. LUT-based logic provides optimized performance and efficiency for data-path, register-intensive, mathematical, or digital signal processing (DSP) designs. Product-term-based logic is optimized for complex combinatorial paths, such as complex state machines. LUT- and product-term-based logic combined with memory functions and a wide variety of MegaCore and AMPP functions make the APEX 20K device architecture uniquely suited for system-on-a-programmable-chip designs. Applications historically requiring a combination of LUT-, product-term-, and memory-based devices can now be integrated into one APEX 20K device.

APEX 20KE devices are a superset of APEX 20K devices and include additional features such as advanced I/O standard support, CAM, additional global clocks, and enhanced ClockLock clock circuitry. In addition, APEX 20KE devices extend the APEX 20K family to 1.5 million gates. APEX 20KE devices are denoted with an "E" suffix in the device name (e.g., the EP20K1000E device is an APEX 20KE device). Table 8 compares the features included in APEX 20K and APEX 20KE devices.

Feature	APEX 20K Devices	APEX 20KE Devices
MultiCore system integration	Full support	Full support
SignalTap logic analysis	Full support	Full support
32/64-Bit, 33-MHz PCI	Full compliance in -1, -2 speed grades	Full compliance in -1, -2 speed grades
32/64-Bit, 66-MHz PCI	-	Full compliance in -1 speed grade
MultiVolt I/O	2.5-V or 3.3-V V _{CCIO} V _{CCIO} selected for device Certain devices are 5.0-V tolerant	1.8-V, 2.5-V, or 3.3-V V _{CCIO} V _{CCIO} selected block-by-block 5.0-V tolerant with use of external resistor
ClockLock support	Clock delay reduction 2× and 4× clock multiplication	Clock delay reduction $m/(n \times v)$ or $m/(n \times k)$ clock multiplication Drive ClockLock output off-chip External clock feedback ClockShift LVDS support Up to four PLLs ClockShift, clock phase adjustment
Dedicated clock and input pins	Six	Eight
I/O standard support	2.5-V, 3.3-V, 5.0-V I/O 3.3-V PCI Low-voltage complementary metal-oxide semiconductor (LVCMOS) Low-voltage transistor-to-transistor logic (LVTTL)	1.8-V, 2.5-V, 3.3-V, 5.0-V I/O 2.5-V I/O 3.3-V PCI and PCI-X 3.3-V Advanced Graphics Port (AGP) Center tap terminated (CTT) GTL+ LVCMOS LVTTL True-LVDS and LVPECL data pins (in EP20K300E and larger devices) LVDS and LVPECL signaling (in all BGA and FineLine BGA devices) LVDS and LVPECL data pins up to 156 Mbps (in -1 speed grade devices) HSTL Class I PCI-X SSTL-2 Class I and II SSTL-3 Class I and II
Memory support	Dual-port RAM FIFO RAM ROM	CAM Dual-port RAM FIFO RAM ROM

All APEX 20K devices are reconfigurable and are 100% tested prior to shipment. As a result, test vectors do not have to be generated for fault coverage purposes. Instead, the designer can focus on simulation and design verification. In addition, the designer does not need to manage inventories of different application-specific integrated circuit (ASIC) designs; APEX 20K devices can be configured on the board for the specific functionality required.

APEX 20K devices are configured at system power-up with data stored in an Altera serial configuration device or provided by a system controller. Altera offers in-system programmability (ISP)-capable EPC1, EPC2, and EPC16 configuration devices, which configure APEX 20K devices via a serial data stream. Moreover, APEX 20K devices contain an optimized interface that permits microprocessors to configure APEX 20K devices serially or in parallel, and synchronously or asynchronously. The interface also enables microprocessors to treat APEX 20K devices as memory and configure the device by writing to a virtual memory location, making reconfiguration easy.

After an APEX 20K device has been configured, it can be reconfigured in-circuit by resetting the device and loading new data. Real-time changes can be made during system operation, enabling innovative reconfigurable computing applications.

APEX 20K devices are supported by the Altera Quartus II development system, a single, integrated package that offers HDL and schematic design entry, compilation and logic synthesis, full simulation and worst-case timing analysis, SignalTap logic analysis, and device configuration. The Quartus II software runs on Windows-based PCs, Sun SPARCstations, and HP 9000 Series 700/800 workstations.

The Quartus II software provides NativeLink interfaces to other industry-standard PC- and UNIX workstation-based EDA tools. For example, designers can invoke the Quartus II software from within third-party design tools. Further, the Quartus II software contains built-in optimized synthesis libraries; synthesis tools can use these libraries to optimize designs for APEX 20K devices. For example, the Synopsys Design Compiler library, supplied with the Quartus II development system, includes DesignWare functions optimized for the APEX 20K architecture.

From Previous Macrocell Product-Macrocell Term Product-Select Term Logic Matrix Parallel Expander Switch Product-Macrocell Term Product-Select Term Logic Matrix Parallel Expander Switch 32 Signals from To Next

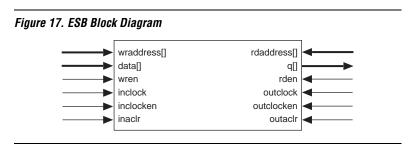
Figure 16. APEX 20K Parallel Expanders

Embedded System Block

Local Interconnect

The ESB can implement various types of memory blocks, including dual-port RAM, ROM, FIFO, and CAM blocks. The ESB includes input and output registers; the input registers synchronize writes, and the output registers can pipeline designs to improve system performance. The ESB offers a dual-port mode, which supports simultaneous reads and writes at two different clock frequencies. Figure 17 shows the ESB block diagram.

Macrocell



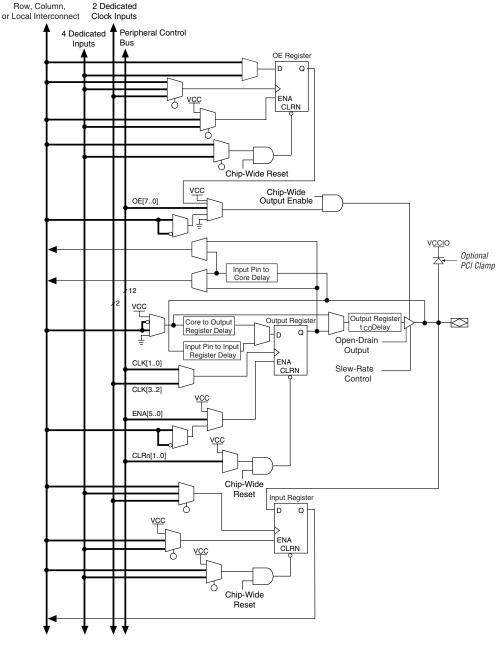


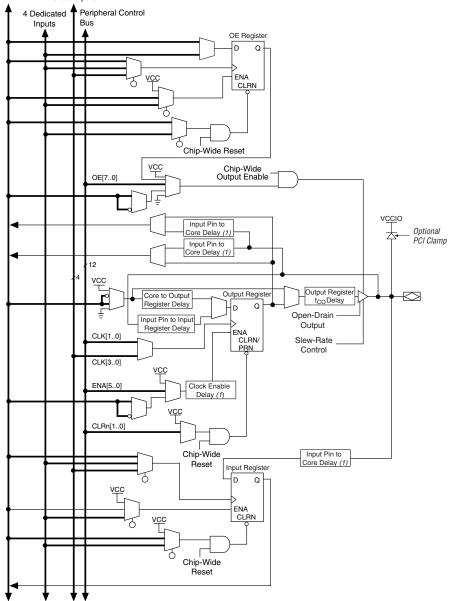
Figure 25. APEX 20K Bidirectional I/O Registers Note (1)

Note to Figure 25:

(1) The output enable and input registers are LE registers in the LAB adjacent to the bidirectional pin.

Figure 26. APEX 20KE Bidirectional I/O Registers Notes (1), (2)

Row, Column, FastRow, 4 Dedicated or Local Interconnect Clock Inputs

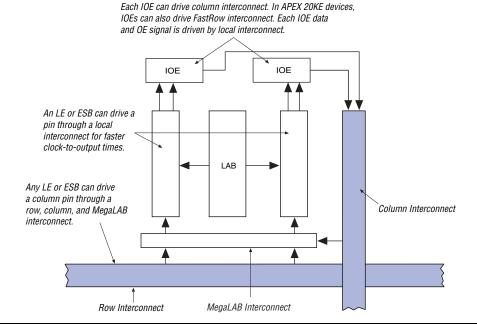


Notes to Figure 26:

- (1) This programmable delay has four settings: off and three levels of delay.
- (2) The output enable and input registers are LE registers in the LAB adjacent to the bidirectional pin.

Figure 28 shows how a column IOE connects to the interconnect.

Figure 28. Column IOE Connection to the Interconnect



Dedicated Fast I/O Pins

APEX 20KE devices incorporate an enhancement to support bidirectional pins with high internal fanout such as PCI control signals. These pins are called Dedicated Fast I/O pins (FAST1, FAST2, FAST3, and FAST4) and replace dedicated inputs. These pins can be used for fast clock, clear, or high fanout logic signal distribution. They also can drive out. The Dedicated Fast I/O pin data output and tri-state control are driven by local interconnect from the adjacent MegaLAB for high speed.

Symbol	Parameter	I/O Standard	-1X Speed Grade		-2X Speed Grade		Units
			Min	Max	Min	Max	
f _{VCO} (4)	Voltage controlled oscillator operating range		200	500	200	500	MHz
f _{CLOCK0}	Clock0 PLL output frequency for internal use		1.5	335	1.5	200	MHz
f _{CLOCK1}	Clock1 PLL output frequency for internal use		20	335	20	200	MHz
f _{CLOCK0_EXT}	Output clock frequency for	3.3-V LVTTL	1.5	245	1.5	226	MHz
_	external clock0 output	2.5-V LVTTL	1.5	234	1.5	221	MHz
		1.8-V LVTTL	1.5	223	1.5	216	MHz
		GTL+	1.5	205	1.5	193	MHz
		SSTL-2 Class	1.5	158	1.5	157	MHz
		SSTL-2 Class	1.5	142	1.5	142	MHz
		SSTL-3 Class	1.5	166	1.5	162	MHz
		SSTL-3 Class	1.5	149	1.5	146	MHz
		LVDS	1.5	420	1.5	350	MHz
f _{CLOCK1_EXT}	Output clock frequency for external clock1 output	3.3-V LVTTL	20	245	20	226	MHz
		2.5-V LVTTL	20	234	20	221	MHz
		1.8-V LVTTL	20	223	20	216	MHz
		GTL+	20	205	20	193	MHz
		SSTL-2 Class I	20	158	20	157	MHz
		SSTL-2 Class	20	142	20	142	MHz
		SSTL-3 Class	20	166	20	162	MHz
		SSTL-3 Class	20	149	20	146	MHz
		LVDS	20	420	20	350	MHz



For DC Operating Specifications on APEX 20KE I/O standards, please refer to *Application Note 117 (Using Selectable I/O Standards in Altera Devices).*

Table 30. APEX 20KE Device Capacitance Note (15)								
Symbol Parameter Conditions Min Max								
C _{IN}	Input capacitance	V _{IN} = 0 V, f = 1.0 MHz		8	pF			
C _{INCLK}	Input capacitance on dedicated clock pin	V _{IN} = 0 V, f = 1.0 MHz		12	pF			
C _{OUT}	Output capacitance	V _{OUT} = 0 V, f = 1.0 MHz		8	pF			

Notes to Tables 27 through 30:

- (1) See the Operating Requirements for Altera Devices Data Sheet.
- (2) Minimum DC input is -0.5 V. During transitions, the inputs may undershoot to -2.0 V or overshoot to 5.75 V for input currents less than 100 mA and periods shorter than 20 ns.
- (3) Numbers in parentheses are for industrial-temperature-range devices.
- (4) Maximum V_{CC} rise time is 100 ms, and V_{CC} must rise monotonically.
- (5) Minimum DC input is -0.5 V. During transitions, the inputs may undershoot to -2.0 V or overshoot to the voltage shown in the following table based on input duty cycle for input currents less than 100 mA. The overshoot is dependent upon duty cycle of the signal. The DC case is equivalent to 100% duty cycle.

Vin Max. Duty Cycle 4.0V 100% (DC) 4.1 90% 4.2 50% 4.3 30% 4.4 17% 4.5 10%

- (6) All pins, including dedicated inputs, clock, I/O, and JTAG pins, may be driven before V_{CCINT} and V_{CCIO} are powered.
- Typical values are for $T_A = 25^{\circ}$ C, $V_{CCINT} = 1.8$ V, and $V_{CCIO} = 1.8$ V, 2.5 V or 3.3 V.
- (8) These values are specified under the APEX 20KE device recommended operating conditions, shown in Table 24 on page 60.
- (9) Refer to Application Note 117 (Using Selectable I/O Standards in Altera Devices) for the V_{IH}, V_{IL}, V_{OH}, V_{OL}, and I_I parameters when VCCIO = 1.8 V.
- (10) The APEX 20KE input buffers are compatible with 1.8-V, 2.5-V and 3.3-V (LVTTL and LVCMOS) signals. Additionally, the input buffers are 3.3-V PCI compliant. Input buffers also meet specifications for GTL+, CTT, AGP, SSTL-2, SSTL-3, and HSTL.
- (11) The I_{OH} parameter refers to high-level TTL, PCI, or CMOS output current.
- (12) The I_{OL} parameter refers to low-level TTL, PCI, or CMOS output current. This parameter applies to open-drain pins as well as output pins.
- (13) This value is specified for normal device operation. The value may vary during power-up.
- (14) Pin pull-up resistance values will be lower if an external source drives the pin higher than V_{CCIO}.
- (15) Capacitance is sample-tested only.

Figure 33 shows the relationship between V_{CCIO} and V_{CCINT} for 3.3-V PCI compliance on APEX 20K devices.

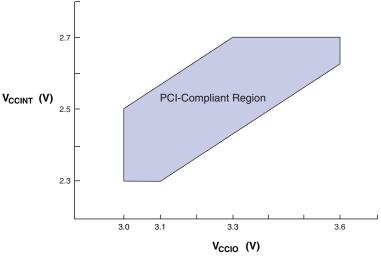


Figure 33. Relationship between V_{CCIO} & V_{CCINT} for 3.3-V PCI Compliance

Figure 34 shows the typical output drive characteristics of APEX 20K devices with 3.3-V and 2.5-V $V_{\rm CCIO}$. The output driver is compatible with the 3.3-V *PCI Local Bus Specification, Revision 2.2* (when VCCIO pins are connected to 3.3 V). 5-V tolerant APEX 20K devices in the -1 speed grade are 5-V PCI compliant over all operating conditions.

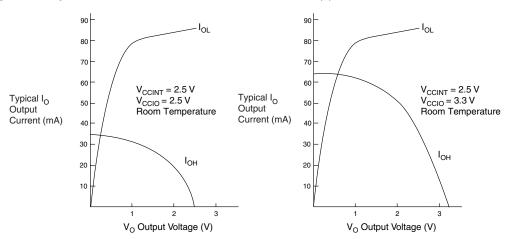


Figure 34. Output Drive Characteristics of APEX 20K Device Note (1)

Note to Figure 34:

(1) These are transient (AC) currents.

Table 31. APEX 20K f _{MAX} Timing Parameters (Part 2 of 2)					
Symbol	Parameter				
t _{ESBDATACO2}	ESB clock-to-output delay without output registers				
t _{ESBDD}	ESB data-in to data-out delay for RAM mode				
t _{PD}	ESB macrocell input to non-registered output	-			
t _{PTERMSU}	ESB macrocell register setup time before clock				
t _{PTERMCO}	ESB macrocell register clock-to-output delay				
t _{F1-4}	Fanout delay using local interconnect				
t _{F5-20}	Fanout delay using MegaLab Interconnect				
t _{F20+}	Fanout delay using FastTrack Interconnect				
t _{CH}	Minimum clock high time from clock pin				
t _{CL}	Minimum clock low time from clock pin				
t _{CLRP}	LE clear pulse width				
t _{PREP}	LE preset pulse width				
t _{ESBCH}	Clock high time				
t _{ESBCL}	Clock low time				
t _{ESBWP}	Write pulse width				
t _{ESBRP}	Read pulse width				

Tables 32 and 33 describe APEX 20K external timing parameters.

Table 32. APEX 20K External Timing Parameters Note (1)				
Symbol	Clock Parameter			
t _{INSU}	Setup time with global clock at IOE register			
t _{INH}	Hold time with global clock at IOE register			
tоитсо	Clock-to-output delay with global clock at IOE register			

Table 33. APEX 20K External Bidirectional Timing Parameters Note (1)						
Symbol	Parameter	Conditions				
t _{INSUBIDIR}	Setup time for bidirectional pins with global clock at same-row or same-column LE register					
t _{INHBIDIR}	Hold time for bidirectional pins with global clock at same-row or same-column LE register					
^t OUTCOBIDIR	Clock-to-output delay for bidirectional pins with global clock at IOE register	C1 = 10 pF				
t _{XZBIDIR}	Synchronous IOE output buffer disable delay	C1 = 10 pF				
t _{ZXBIDIR}	Synchronous IOE output buffer enable delay, slow slew rate = off	C1 = 10 pF				

Tables 40 through 42 show the $f_{\mbox{\scriptsize MAX}}$ timing parameters for EP20K100, EP20K200, and EP20K400 APEX 20K devices.

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Units	
	Min	Max	Min	Max	Min	Max		
t _{SU}	0.5		0.6		0.8		ns	
t _H	0.7		0.8		1.0		ns	
t _{CO}		0.3		0.4		0.5	ns	
t _{LUT}		0.8		1.0		1.3	ns	
t _{ESBRC}		1.7		2.1		2.4	ns	
t _{ESBWC}		5.7		6.9		8.1	ns	
t _{ESBWESU}	3.3		3.9		4.6		ns	
t _{ESBDATASU}	2.2		2.7		3.1		ns	
t _{ESBDATAH}	0.6		0.8		0.9		ns	
t _{ESBADDRSU}	2.4		2.9		3.3		ns	
t _{ESBDATACO1}		1.3		1.6		1.8	ns	
t _{ESBDATACO2}		2.6		3.1		3.6	ns	
t _{ESBDD}		2.5		3.3		3.6	ns	
t _{PD}		2.5		3.0		3.6	ns	
t _{PTERMSU}	2.3		2.6		3.2		ns	
t _{PTERMCO}		1.5		1.8		2.1	ns	
t _{F1-4}		0.5		0.6		0.7	ns	
t _{F5-20}		1.6		1.7		1.8	ns	
t _{F20+}		2.2		2.2		2.3	ns	
t _{CH}	2.0		2.5		3.0		ns	
t _{CL}	2.0		2.5		3.0		ns	
t _{CLRP}	0.3		0.4		0.4		ns	
t _{PREP}	0.5		0.5		0.5		ns	
t _{ESBCH}	2.0		2.5		3.0		ns	
t _{ESBCL}	2.0		2.5		3.0		ns	
t _{ESBWP}	1.6		1.9		2.2		ns	
t _{ESBRP}	1.0		1.3		1.4	_	ns	

Symbol	-1 Speed Grade		-2 Spee	-2 Speed Grade		d Grade	Unit
	Min	Max	Min	Max	Min	Max	
t _{INSUBIDIR} (1)	1.9		2.3		2.6		ns
t _{INHBIDIR} (1)	0.0		0.0		0.0		ns
t _{OUTCOBIDIR} (1)	2.0	4.6	2.0	5.6	2.0	6.8	ns
t _{XZBIDIR} (1)		5.0		5.9		6.9	ns
t _{ZXBIDIR} (1)		5.0		5.9		6.9	ns
t _{INSUBIDIR} (2)	1.1		1.2		-		ns
t _{INHBIDIR} (2)	0.0		0.0		-		ns
t _{OUTCOBIDIR} (2)	0.5	2.7	0.5	3.1	-	_	ns
t _{XZBIDIR} (2)		4.3		5.0		_	ns
t _{ZXBIDIR} (2)		4.3		5.0		_	ns

Table 47. EP20K400 External Timing Parameters									
Symbol	-1 Speed Grade		-2 Spec	-2 Speed Grade		-3 Speed Grade			
	Min	Max	Min	Max	Min	Max	_		
t _{INSU} (1)	1.4		1.8		2.0		ns		
t _{INH} (1)	0.0		0.0		0.0		ns		
t _{OUTCO} (1)	2.0	4.9	2.0	6.1	2.0	7.0	ns		
t _{INSU} (2)	0.4		1.0		-		ns		
t _{INH} (2)	0.0		0.0		_		ns		
t _{OUTCO} (2)	0.5	3.1	0.5	4.1	_	_	ns		

Table 48. EP20K400 External Bidirections	I Timina	Parameters 1 4 1
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Symbol	-1 Speed Grade		-2 Spee	ed Grade	-3 Spe	Unit	
	Min	Max	Min	Max	Min	Max	
t _{INSUBIDIR} (1)	1.4		1.8		2.0		ns
t _{INHBIDIR} (1)	0.0		0.0		0.0		ns
t _{OUTCOBIDIR} (1)	2.0	4.9	2.0	6.1	2.0	7.0	ns
t _{XZBIDIR} (1)		7.3		8.9		10.3	ns
t _{ZXBIDIR} (1)		7.3		8.9		10.3	ns
t _{INSUBIDIR} (2)	0.5		1.0		-		ns
t _{INHBIDIR} (2)	0.0		0.0		-		ns
toutcobidir (2)	0.5	3.1	0.5	4.1	-	-	ns
t _{XZBIDIR} (2)		6.2		7.6		-	ns
t _{ZXBIDIR} (2)		6.2		7.6		_	ns

Notes to Tables 43 through 48:

- (1) This parameter is measured without using ClockLock or ClockBoost circuits.
- (2) This parameter is measured using ClockLock or ClockBoost circuits.

Tables 49 through 54 describe f_{MAX} LE Timing Microparameters, f_{MAX} ESB Timing Microparameters, f_{MAX} Routing Delays, Minimum Pulse Width Timing Parameters, External Timing Parameters, and External Bidirectional Timing Parameters for EP20K30E APEX 20KE devices.

Table 49. EP20K30E f _{MAX} LE Timing Microparameters										
Symbol	-	1	-	2	-;	Unit				
	Min	Max	Min	Max	Min	Max				
t _{SU}	0.01		0.02		0.02		ns			
t _H	0.11		0.16		0.23		ns			
t _{CO}		0.32		0.45		0.67	ns			
t _{LUT}		0.85		1.20		1.77	ns			

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t _{INSUBIDIR}	2.77		2.91		3.11		ns
t _{INHBIDIR}	0.00		0.00		0.00		ns
toutcobidir	2.00	4.84	2.00	5.31	2.00	5.81	ns
t _{XZBIDIR}		6.47		7.44		8.65	ns
t _{ZXBIDIR}		6.47		7.44		8.65	ns
t _{INSUBIDIRPLL}	3.44		3.24		-		ns
t _{INHBIDIRPLL}	0.00		0.00		-		ns
^t OUTCOBIDIRPLL	0.50	3.37	0.50	3.69	-	-	ns
txzbidirpll		5.00		5.82		-	ns
t _{ZXBIDIRPLL}		5.00		5.82		-	ns

Tables 61 through 66 describe f_{MAX} LE Timing Microparameters, f_{MAX} ESB Timing Microparameters, f_{MAX} Routing Delays, Minimum Pulse Width Timing Parameters, External Timing Parameters, and External Bidirectional Timing Parameters for EP20K100E APEX 20KE devices.

Table 61. EP20K100E f _{MAX} LE Timing Microparameters										
Symbol	-	1	-	2	-1	Unit				
	Min	Max	Min	Max	Min	Max				
t _{SU}	0.25		0.25		0.25		ns			
t _H	0.25		0.25		0.25		ns			
t _{CO}		0.28		0.28		0.34	ns			
t _{LUT}		0.80		0.95		1.13	ns			

Table 62. EP20K	I GOL IMAX LOL	, iming mid	1		Ī		1
Symbol	-	1		-2	-:	3	Unit
	Min	Max	Min	Max	Min	Max	
t _{ESBARC}		1.61		1.84		1.97	ns
t _{ESBSRC}		2.57		2.97		3.20	ns
t _{ESBAWC}		0.52		4.09		4.39	ns
t _{ESBSWC}		3.17		3.78		4.09	ns
t _{ESBWASU}	0.56		6.41		0.63		ns
t _{ESBWAH}	0.48		0.54		0.55		ns
t _{ESBWDSU}	0.71		0.80		0.81		ns
t _{ESBWDH}	.048		0.54		0.55		ns
t _{ESBRASU}	1.57		1.75		1.87		ns
t _{ESBRAH}	0.00		0.00		0.20		ns
t _{ESBWESU}	1.54		1.72		1.80		ns
t _{ESBWEH}	0.00		0.00		0.00		ns
t _{ESBDATASU}	-0.16		-0.20		-0.20		ns
t _{ESBDATAH}	0.13		0.13		0.13		ns
t _{ESBWADDRSU}	0.12		0.08		0.13		ns
t _{ESBRADDRSU}	0.17		0.15		0.19		ns
t _{ESBDATACO1}		1.20		1.39		1.52	ns
t _{ESBDATACO2}		2.54		2.99		3.22	ns
t _{ESBDD}		3.06		3.56		3.85	ns
t _{PD}		1.73		2.02		2.20	ns
t _{PTERMSU}	1.11		1.26		1.38		ns
t _{PTERMCO}		1.19		1.40		1.08	ns

Table 63. EP2	Table 63. EP20K100E f _{MAX} Routing Delays											
Symbol	-	1	-	-2	-3		Unit					
	Min	Max	Min	Max	Min	Max						
t _{F1-4}		0.24		0.27		0.29	ns					
t _{F5-20}		1.04		1.26		1.52	ns					
t _{F20+}		1.12		1.36		1.86	ns					

Tables 85 through 90 describe f_{MAX} LE Timing Microparameters, f_{MAX} ESB Timing Microparameters, f_{MAX} Routing Delays, Minimum Pulse Width Timing Parameters, External Timing Parameters, and External Bidirectional Timing Parameters for EP20K400E APEX 20KE devices.

Table 85. EP2	Table 85. EP20K400E f _{MAX} LE Timing Microparameters										
Symbol	-1 Spee	d Grade	-2 Spec	ed Grade	-3 Spee	-3 Speed Grade					
	Min	Max	Min	Max	Min	Max]				
t _{SU}	0.23		0.23		0.23		ns				
t _H	0.23		0.23		0.23		ns				
t _{CO}		0.25		0.29		0.32	ns				
t _{LUT}		0.70		0.83		1.01	ns				

Symbol	-1 Spee	d Grade	-2 Spee	d Grade	-3 Spee	Unit	
	Min	Max	Min	Max	Min	Max	
t _{INSUBIDIR}	2.93		3.23		3.44		ns
t _{INHBIDIR}	0.00		0.00		0.00		ns
toutcobidir	2.00	5.25	2.00	5.79	2.00	6.32	ns
t _{XZBIDIR}		5.95		6.77		7.12	ns
tzxbidir		5.95		6.77		7.12	ns
t _{INSUBIDIRPLL}	4.31		4.76		-		ns
tinhbidirpll	0.00		0.00		-		ns
toutcobidirpll	0.50	2.25	0.50	2.45	-	-	ns
txzbidirpll		2.94		3.43		-	ns
tzxbidirpll		2.94		3.43		-	ns

Tables 91 through 96 describe f_{MAX} LE Timing Microparameters, f_{MAX} ESB Timing Microparameters, f_{MAX} Routing Delays, Minimum Pulse Width Timing Parameters, External Timing Parameters, and External Bidirectional Timing Parameters for EP20K600E APEX 20KE devices.

Table 91. EP20K600E f _{MAX} LE Timing Microparameters										
Symbol	-1 Spee	d Grade	-2 Spee	ed Grade	-3 Spee	-3 Speed Grade				
	Min	Max	Min	Max	Min	Max				
t _{SU}	0.16		0.16		0.17		ns			
t _H	0.29		0.33		0.37		ns			
t _{CO}		0.65		0.38		0.49	ns			
t _{LUT}		0.70		1.00		1.30	ns			

Table 99. EP2	Table 99. EP20K1000E f _{MAX} Routing Delays											
Symbol	-1 Spee	d Grade	-2 Spec	ed Grade	-3 Speed Grade		Unit					
	Min	Max	Min	Max	Min	Max						
t _{F1-4}		0.27		0.27		0.27	ns					
t _{F5-20}		1.45		1.63		1.75	ns					
t _{F20+}		4.15		4.33		4.97	ns					

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Spee	Unit	
	Min	Max	Min	Max	Min	Max	
t _{CH}	1.25		1.43		1.67		ns
t _{CL}	1.25		1.43		1.67		ns
t _{CLRP}	0.20		0.20		0.20		ns
t _{PREP}	0.20		0.20		0.20		ns
t _{ESBCH}	1.25		1.43		1.67		ns
t _{ESBCL}	1.25		1.43		1.67		ns
t _{ESBWP}	1.28		1.51		1.65		ns
t _{ESBRP}	1.11		1.29		1.41		ns

Symbol	-1 Speed Grade		-2 Spee	-2 Speed Grade		-3 Speed Grade	
	Min	Max	Min	Max	Min	Max	
t _{INSU}	2.70		2.84		2.97		ns
t _{INH}	0.00		0.00		0.00		ns
t _{OUTCO}	2.00	5.75	2.00	6.33	2.00	6.90	ns
t _{INSUPLL}	1.64		2.09		=		ns
t _{INHPLL}	0.00		0.00		=		ns
t _{OUTCOPLL}	0.50	2.25	0.50	2.99	-	-	ns